Grinding Process and Measurement for Optical elements

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Background



- 3.8m Telescope Project
 - The project started in 2008 to study the segmented mirror techniques and to fulfill the scientific potential in domestic site, Okayama.
 - Developing high precision grinding process is one of the main technical targets for 18 segments and large convex secondary mirror.

Grinding Process

Grinding Machine



Facility (Nano Optonics Energy)





Grinding Machine (N2C-1300D)

Grinding of Large Optics

- Size: Φ610
- From:
- Material: Clearseram
- Processing time:
- Flat Clearseram several hours



First Grinding P-V=0.7 um



Grinding Large Optics Segmented Mirror

- R: 10,000
- K: -1.035
- D: ~1000

t : 40-60 (flat backside) Material: Clearseram-z



Problem of Direct Support



• The error induced by a direct support is several microns in case of large but thin optics.

Support System

- When the segment sits directly on the table, the segment is deformed by figure errors of the table and back side of the segment, and inconsistency of thermal expansion between the table and segment.
- Ideally the segment is on a kinematic support (whiffletree) under processing, however the whiffletree is not sound against grinding force and is complicated to FEM analysis.

Note: Whiffletree support system works well under the polishing process which controls polishing pressure and time.

Three Fixed and Spring Support

- Three fixed points are employed for kinematic support.
- 24 springs are for assist of the support and to decrease friction between the segment and fixed points
- The deformation induced by grinding pressure was simulated beforehand, and then a stone is controlled to correct the deformation.



Three Fixed and Spring Support





Deformation map with grinding force of 5N P-V = 5 um

The black points show the position of fixed points

Figure Error without deformation correction Each color of the lines corresponds to that of the right hand figure (1div = 1 um)





Grinding with correction

Each line are described in a same manner of the preceding page

(1div = 1 um)

Processing time: 10 days The time will be reduced to several days by optimization of grinding method already developed.



Error map after flash polishing -1 um to 1 um 11/33

Result

- Smooth and centrosymmetric error.
- Some high frequency error



Polishing

Polishing tools on the grinding machine



Error map after final polishing -0.1 um to 0.1 um



PSF(simulation) Left: ideal, Right: this work



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Measuerement

On the Machine Measurement System Interferometer



CGH Interferometer





Designed grating pattern produces intentionally distorted wave front

CGH (Computer Generated Hologram)



CGH for the inner segment Each line represents 30 lines in the real pattern

CGH Interferometer



Reference beam Goes through the CGH as 0th order and back through as 1st order

Test beam

Goes through the CGH as $1^{\mbox{th}}$ order and back through as $0^{\mbox{st}}$ order

- Semi common pass
 → Robust against turbulence and vibration
- 0th order of reflected test beam
 →Easy to design the imaging lens and to obtain high spatial resolution

On the Machine Measurement System Probe Scan (under development)



Background

- Interferometer is weak in measuring convex surface
 - ex. Secondary mirror of Richey Cretien and some optical elements in instruments
- Grinding machine has very high precision.
 - More precise than any 3-D measurement system
- University of Arizona has developed mechanical profilometer.
- Three orthogonal axes measurement system by using the grinding machine is useful to produce free-form optics (ex. large off axis optics, image slicer, x-ray telescope optics)

Background Swing Arm Profilometer



Fig. 1. Geometry of the swing-arm profilometer system

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Background **Swing Arm Profilometer**

Fizeau RMS=35.7 nm



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200

150

0.1

0.05

0

-0.05

-0.1

Specification of the Grinding Machine

- 4 axes synchronous control (x, y, z, B- axis)
 - 5 axes in maximum (+ C -axis)



Specification of the Grinding Machine

- Work size $\phi 1400$ (TMT segment size)
- Linearity(P-V) 0.38um/1000mm (x)
 0.32um/200mm (y)
 0.35um/1000mm(z)
 - 0.1um/rotation (B wobble)
- Positional Precision (P-V)

0.40um/2250mm(x) 0.17um/280mm(y)

0.16 um/1000 mm(z)



Example X linearity



Typically P-V = 0.1 um the value includes the error of the gage

Specification of the Grinding Machine

• B-axis

- Synchronous motion precision
- X-Y 0.18um
- X-Z 0.15um
- Y-Z 0.15um



Specification of the Grinding Machine

• Rpeatability: P-V < 0.1 um



Measurement by the Grinding Machine with a Probe





Preliminary Result

- Single probe
- Two axes synchronous control
- Measuring time : 1 hour



Spherical mirror Φ150,R1600



Scanning Path: 4 radial lines and 25 circles

Preliminary Result



With tilt and power removed

Future Work

- Algorithm (maximum likelihood at stitching points, interpolation for producing a continuous surface)
- Scanning path
- Multi probe system (three serial point method)
- Stability of the probes

Summary Potential of the Facility

- Excellent grinding machine
 - Freeform
 - High precision
 - Large work size

- Measurement system
 - CGH interferometer for off-axis, aspheric, but concave optics
 - Mechanical probe has a potential for freeform optics